

AP80N30W-VB Datasheet

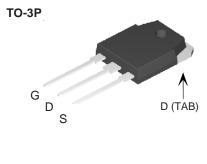
N-Channel 600V(D-S) Super Junction Power MOSFET

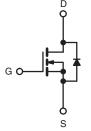
PRODUCT SUMMARY				
V_{DS} (V) at T_J max.	600			
R _{DS(on)} at 25 °C (Ω)	V _{GS} = 10 V	0.06		
Q _g max. (nC)	273			
Q _{gs} (nC)	46			
Q _{gd} (nC)	79			
Configuration	Single			

FEATURES

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)







N-Channel MOSFET

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	600	V	
Gate-Source Voltage			V_{GS}	± 30	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	$T_C = 25 \degree C$ $T_C = 100 \degree C$	- I _D	47		
		T _C = 100 °C		30	Α	
Pulsed Drain Current ^a			I _{DM}	142		
Linear Derating Factor				3.3	W/°C	
Single Pulse Avalanche Energy b			E _{AS}	1410	mJ	
Maximum Power Dissipation			P_{D}	415	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 125 °C		dV/dt	37	V/ns	
Reverse Diode dV/dt ^d	erse Diode dV/dt ^d		αν/ατ	9		
Soldering Recommendations (Peak Temperature) c	for 10 s			300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 10 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	40	°C/W	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.3	G/ VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$		2	-	4	V
0.1. 0	I _{GSS}	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-Source Leakage			$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μA
Zone Ooto Voltana Dusia Ormant	,	V _{DS} = 650 V, V _{GS} = 0 V V _{DS} = 520 V, V _{GS} = 0 V, T _J = 125 °C		-	-	1	μА
Zero Gate Voltage Drain Current	I _{DSS}			-	-	25	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 24 A	-	0.06	=.	Ω
Forward Transconductance	9 _{fs}	V _{DS} = 30 V, I _D = 24 A		-	16.7	-	S
Dynamic		-					•
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		-	5682	-	pF
Output Capacitance	C _{oss}			-	251	-	
Reverse Transfer Capacitance	C _{rss}			-	1	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{DS} = 0 V to 520 V, V _{GS} = 0 V		-	192	-	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	665	-	
Total Gate Charge	Q_g			-	182	273	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 24 \text{ A}, V_{DS} = 520 \text{ V}$		46	-	nC
Gate-Drain Charge	Q_{gd}			-	79	-	
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 520 \text{ V}, I_{D} = 6 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	47	94	- ns
Rise Time	t _r			-	87	131	
Turn-Off Delay Time	t _{d(off)}			-	156	234	
Fall Time	t _f			-	103	206	
Gate Input Resistance	R _g	f = 1 MHz, open drain		=	0.64	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	47	
Pulsed Diode Forward Current	I _{SM}			-	-	139	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 24 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	$T_J = 25 \text{ °C, } I_F = I_S = 24 \text{ A,}$ $dI/dt = 100 \text{ A/µs, } V_R = 25 \text{ V}$		-	753	1506	ns
Reverse Recovery Charge	Q _{rr}			-	14	28	μC
Reverse Recovery Current	I _{RRM}			_	28	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

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TYPCIAL CHARACTERISTICS (25 °C, unless otherwise noted)

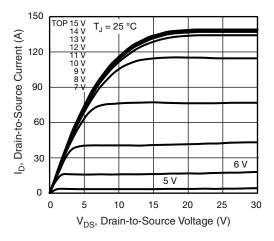


Fig. 1 - Typical Output Characteristics

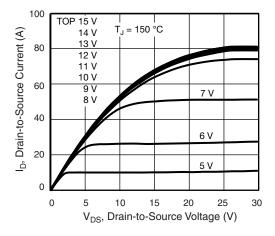


Fig. 2 - Typical Output Characteristics

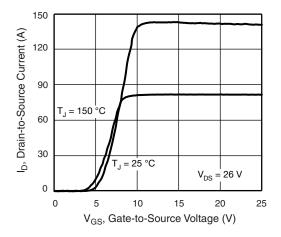


Fig. 3 - Typical Transfer Characteristics

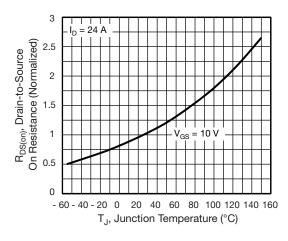


Fig. 4 - Normalized On-Resistance vs. Temperature

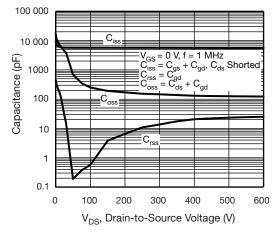


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

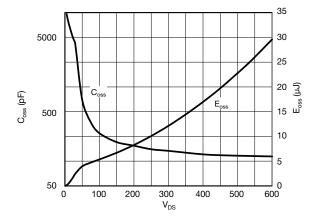


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



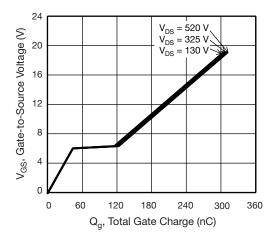


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

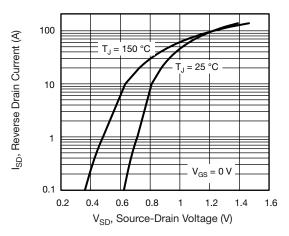


Fig. 8 - Typical Source-Drain Diode Forward Voltage

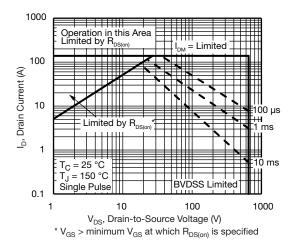


Fig. 9 - Maximum Safe Operating Area

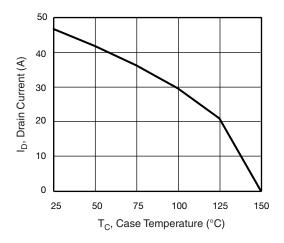


Fig. 10 - Maximum Drain Current vs. Case Temperature

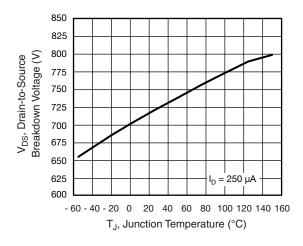


Fig. 11 - Temperature vs. Drain-to-Source Voltage



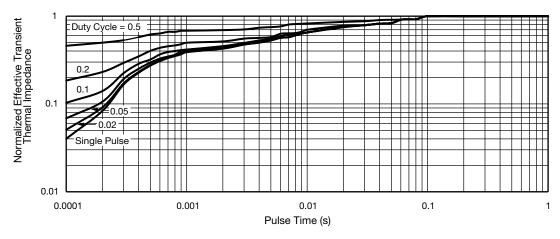


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

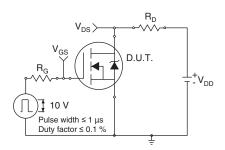


Fig. 13 - Switching Time Test Circuit

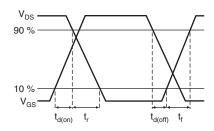


Fig. 14 - Switching Time Waveforms

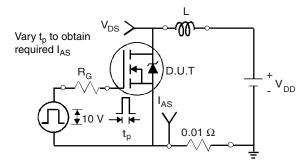


Fig. 15 - Unclamped Inductive Test Circuit

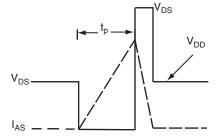


Fig. 16 - Unclamped Inductive Waveforms

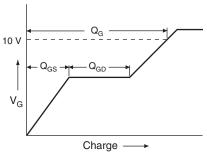


Fig. 17 - Basic Gate Charge Waveform

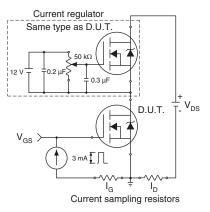
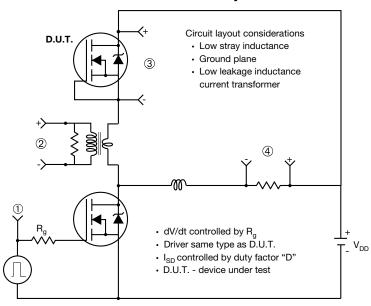


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



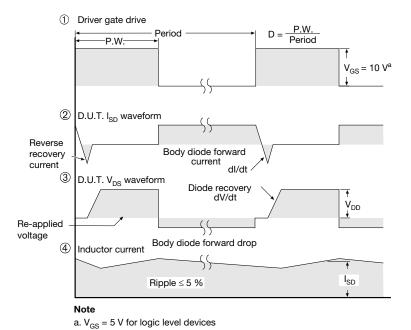


Fig. 19 - For N-Channel

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